



100GEL C2M Channel Reach Options & System Design Impacts

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100GEL C2M Channel Requirements (Cisco Proposal in Rosemont Meeting)

- Target ball to ball IL $\leq 12\text{dB}$ @ 26.56GHz :
 - To avoid using heavy receiver inside the optical modules \rightarrow lower module power consumption
 - Make 100GEL C2M link budget work with 100GEL CR \rightarrow twinax Cu cables support upto 2 m (see Goergen_100GEL_02_0318)
 - **ball to ball 30dB @26.56GHz, bump to bump 36dB @26.56GHz**
- Overall IL target should allow reasonable trace length with minimum 5" to reduce # of retimers at front ports
- Include present & next generation packaging and PCB technologies

What Have Been Decided in Rosemont Meeting

- Define a single-lane 100 Gb/s PHY for operation over electrical backplanes supporting an insertion loss \leq **28** dB at **26.56** GHz.
- Define a single-lane 100 Gb/s PHY for operation over twin-axial copper cables with lengths up to at least **2** m.

100GEL C2M & CR Link Budget Original Proposal

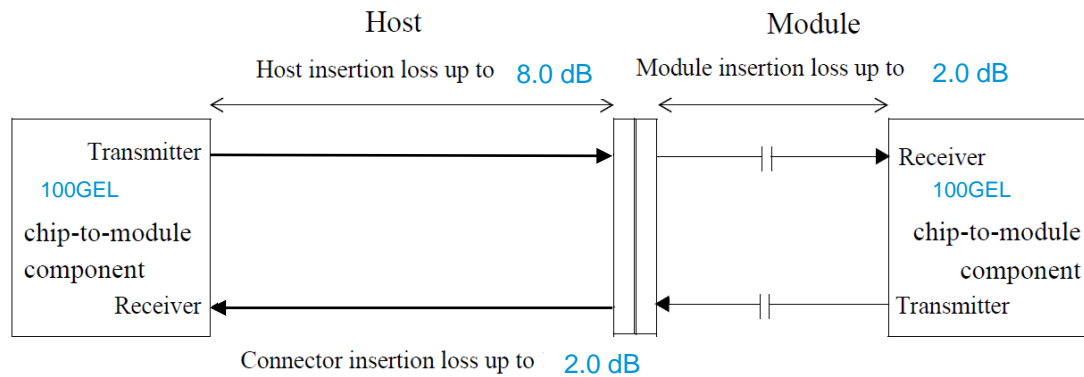


Figure 1: 100GEL C2M insertion loss budget at 26.56 GHz

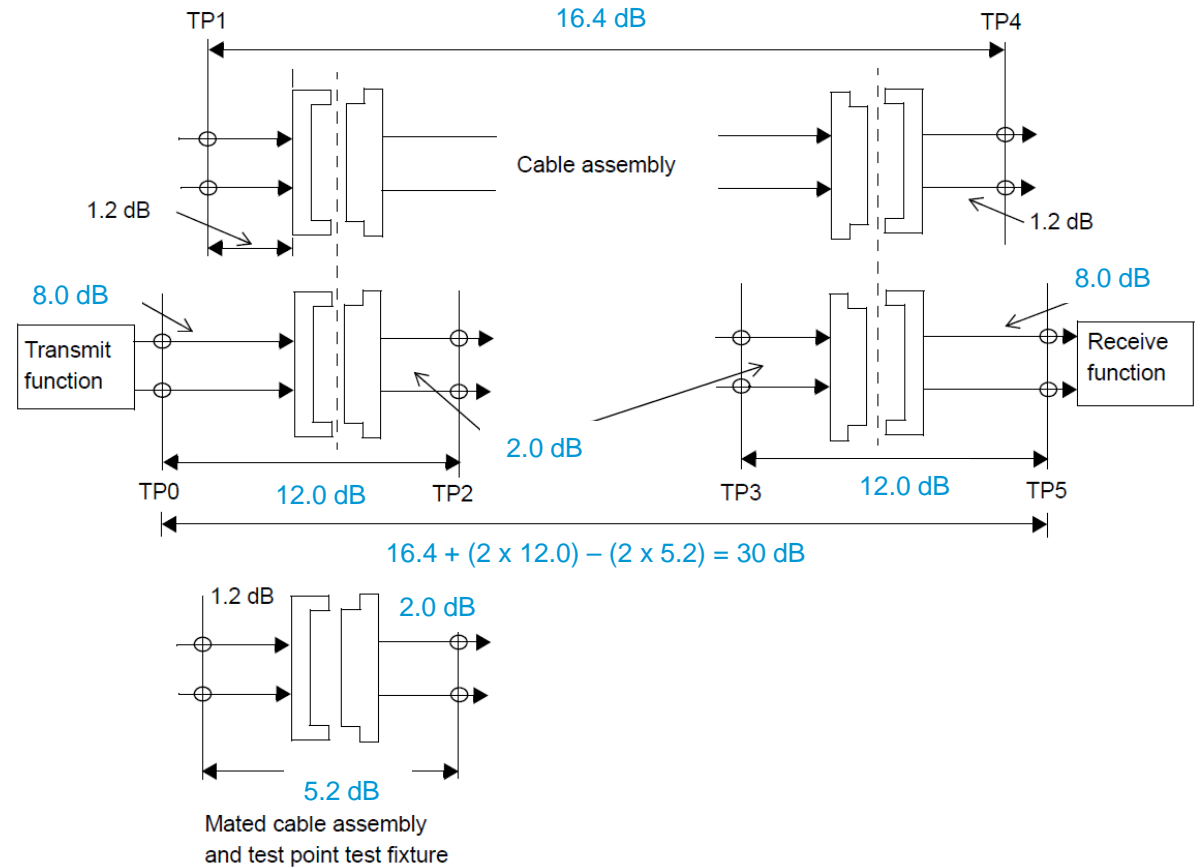


Figure 2: 100GEL CR 30dB insertion loss budget at 26.56 GHz

100GEL C2M & 100GEL CR Link Budget Adjusted Proposal

- Tighten host PCB budget, from 8.0 dB to 7.5dB
- Tighten connector only loss, from 2.0 dB to 1.5 dB
- Loosen Module PCB or HCB loss, from 2.0dB to 2.5dB

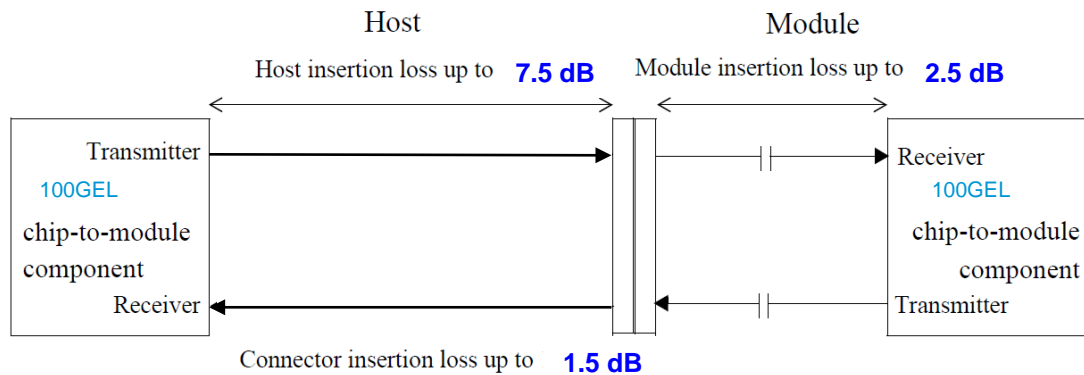


Figure 1: 100GEL C2M **11.5dB** insertion loss budget at 26.56 GHz

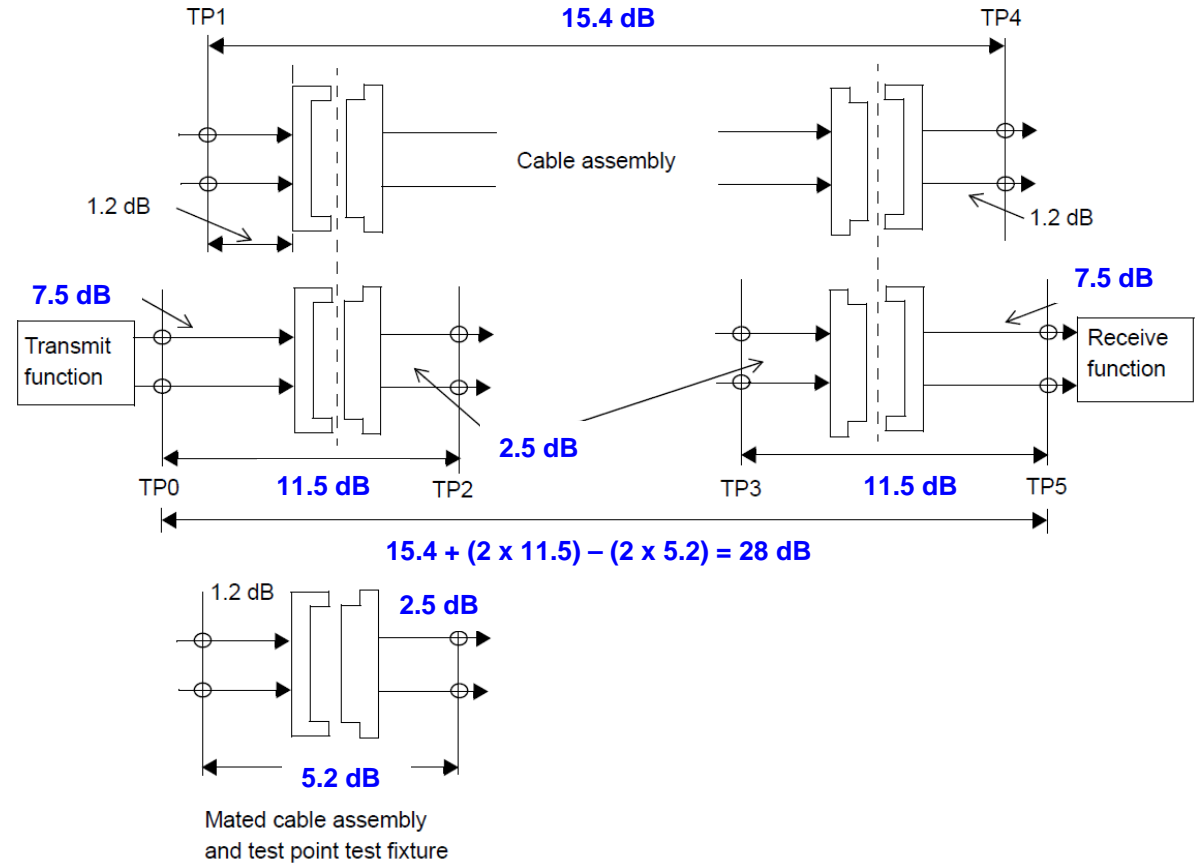


Figure 2: 100GEL CR **28dB** insertion loss budget at 26.56 GHz

Why 7.5dB is Required for Host PCB Budget ?

- With Meg-7N material, 4.5mil trace IL at HT is measured to be 1.24 dB/in at 28 GHz
- For each front port channel there will be 2 set of vias (at host ASIC BGA footprint & at I/O connector footprint) with stripline routing
 - Footprint via with 7.9mil drill & 130mil thick stackup is simulated to be 0.68 dB at 28 GHz
- Total host PCB budget = $(5 \times 1.24 + 2 \times 0.68) = \underline{\underline{7.56 \text{ dB}}}$

100GEL C2M Channel Options

- 3 Options in consideration
 - Option 1: 11-12dB VSR-like reach target
 - Symmetrical link budget on switch side (12dB) & NIC side (12dB)
 - Same port can support 2m DAC
 - Option 2: 14-16dB SR-like reach target
 - Asymmetrical link budget - switch side (15dB) & NIC side (9dB)
 - In switch-to-switch case, this is equiv. to Option III in “ghiasi_100GEL_adhoc_01_050918” which require separate switch host design for 2m DAC support
 - Option 3: 18-20dB MR-like reach target
 - Extended reach for optical interface
 - No DAC support

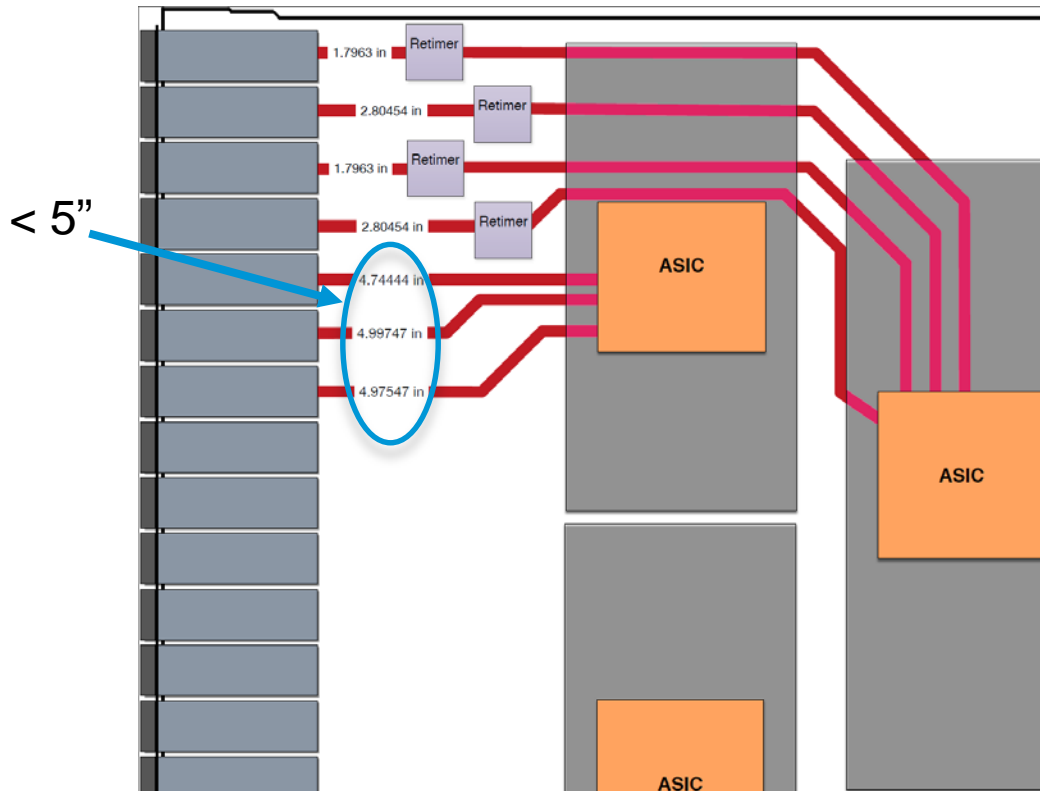
Option 1: 11-12 dB VSR-like Reach Target (1)

- Pros:
 - Can support both Cu and Optics in the same port (Universal port), similar to what are accustomed to today
 - Benefits lower power optical module design (simple serdes)
 - 100 – 300 mW/ch power saving compared to MR-like serdes
 - May need to add PHY device anyhow on every port to support MACsec or other features
 - Offers flexibility in system designs, i.e. for channel > 5", can use retimers or intra-box cables (see next slide), belly to belly module connector, etc
- Cons:
 - Potential impact on system cooling when using intra-box cables
 - System cost increase using retimer or intra-box cables
 - Require chiplet or innovative packaging technique to reduce package loss

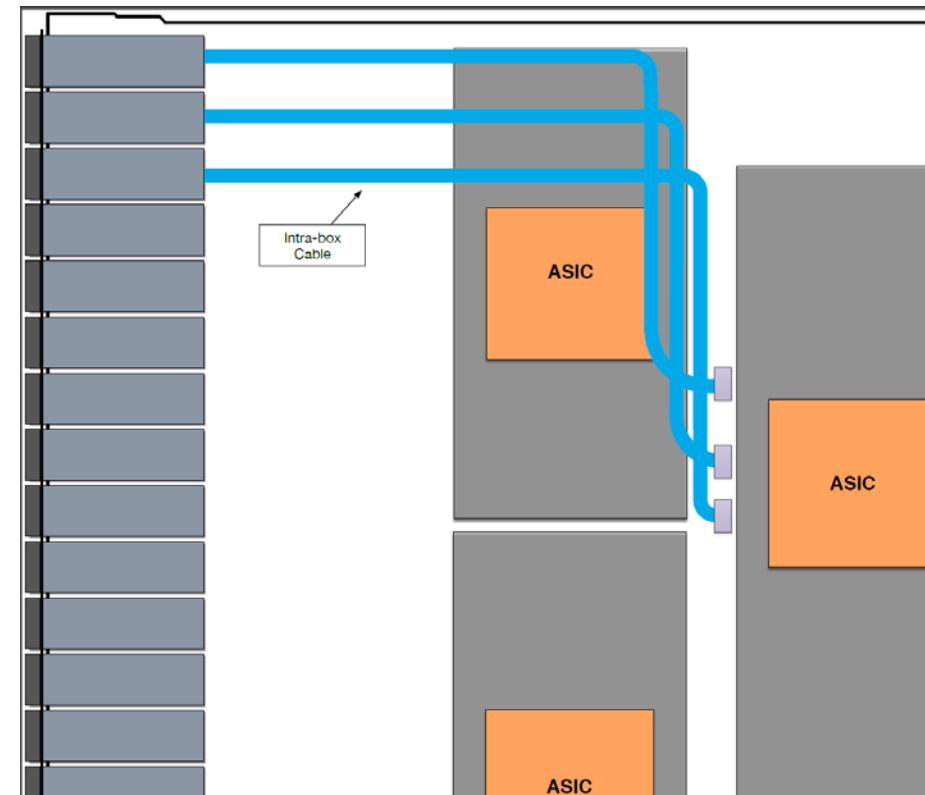
Option 1: 11-12 dB VSR-like Reach Target (2)

- Universal port design on multi-ASIC line-card to support both Optics and 2m DAC
- The diagram depicts the actual placement and routed trace length

Edge ports use retimers



Edge ports use intra-box cables

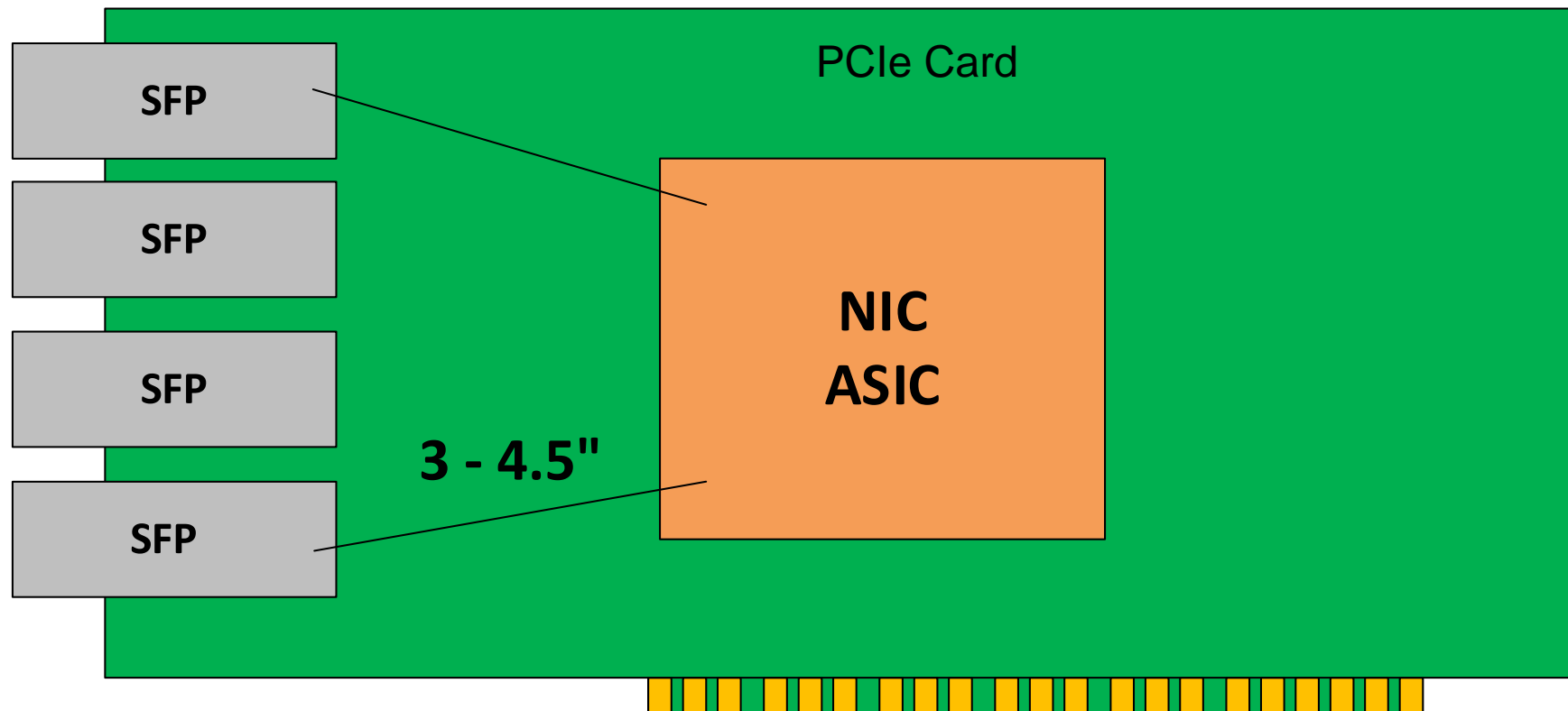


Option 2: 14-16 dB SR-like Reach Target (1)

- Pros:
 - Allow longer host PCB trace for Optics (upto 8”), much fewer retimers or intra-box cables
 - Less impact on system cooling
 - System design cost advantage (less retimers)
 - All the flexibilities in option 1 plus a choice for the system designers to optimize the non-DAC case
- Cons:
 - Switch to switch 2m DAC support doesn't work
 - More complex Rx design in module CDR
 - Serdes power penalty (need serdes suppliers to provide incremental power increase)
 - Most Serdes vendors are not considering to design for this SR-like Serdes at present time
 - More expensive for rack server NIC card, may need to add retimer for >3” trace length (see next slide)

Option 2: 14-16 dB SR-like Reach Target (2)

- Rack Server PCIe NIC Card:
 - Ethernet SFP Port typical trace lengths of 3 – 4.5” based on today NIC card implementations. Potential trace length reduction to 4” depends on ASIC pin-out and board placement



Option 3: 18-20 dB MR-like Reach Target

- Pros:
 - Allow even longer host PCB trace (upto 11”) for Optics
 - No retimers or intra-box cables needed (which is the main goal), lower system cost
 - Less impact on system cooling without intra-box cables
- Cons:
 - **No support for 2m DAC (against the adopted objective !)**
 - Very complex Rx design in module CDR → Power penalty
 - Significant power increase compared to VSR (upto 1.2W added serdes power for a 400G module)
 - Impact on the design of certain PMDs (exceeding module power envelope)
 - Serdes may require link training (in-band or out-band)

Summary

- Our preference for C2M reach is Option 1 with 11-12dB which aligns with 2m DAC objective, and gives simple product consumption for DAC cables (switch to switch, switch to server, server to server)
- We are still studying Serdes design feasibility and module design implication for Option 2, but have concern in product consumption and impact to the server design
- Option 3 with MR Serdes is not a viable solution

Thank You !

Backup Slides

400GAUI-8 C2M IL Budget

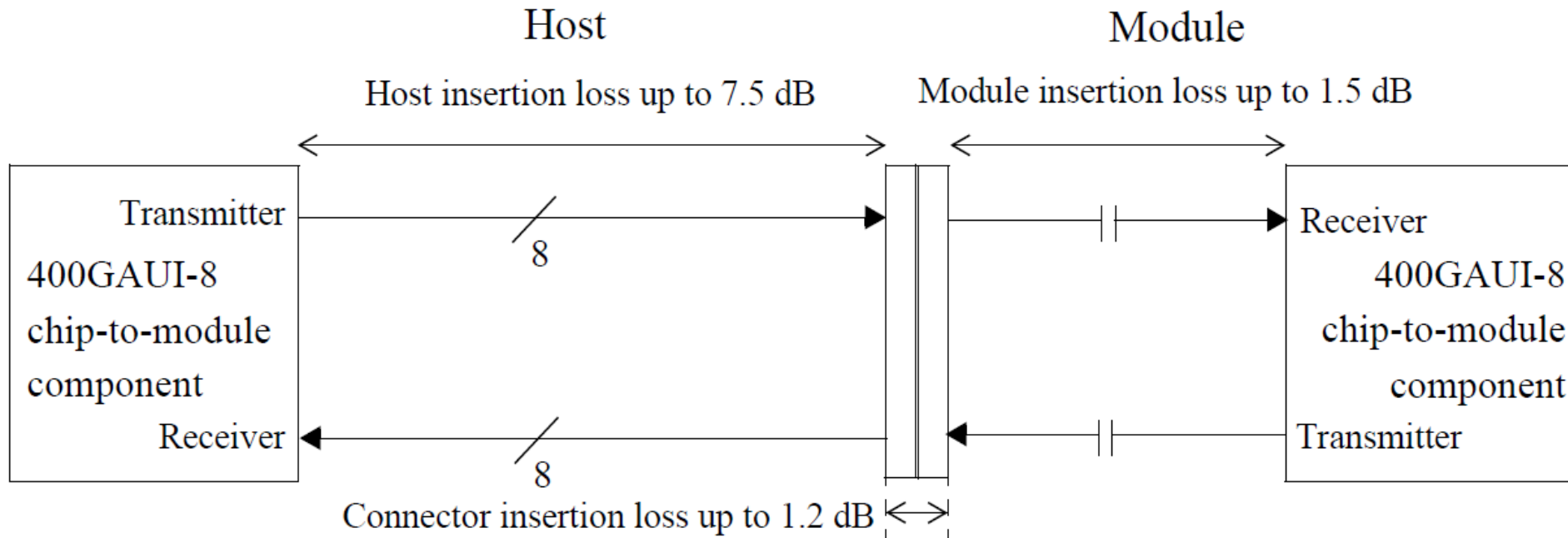
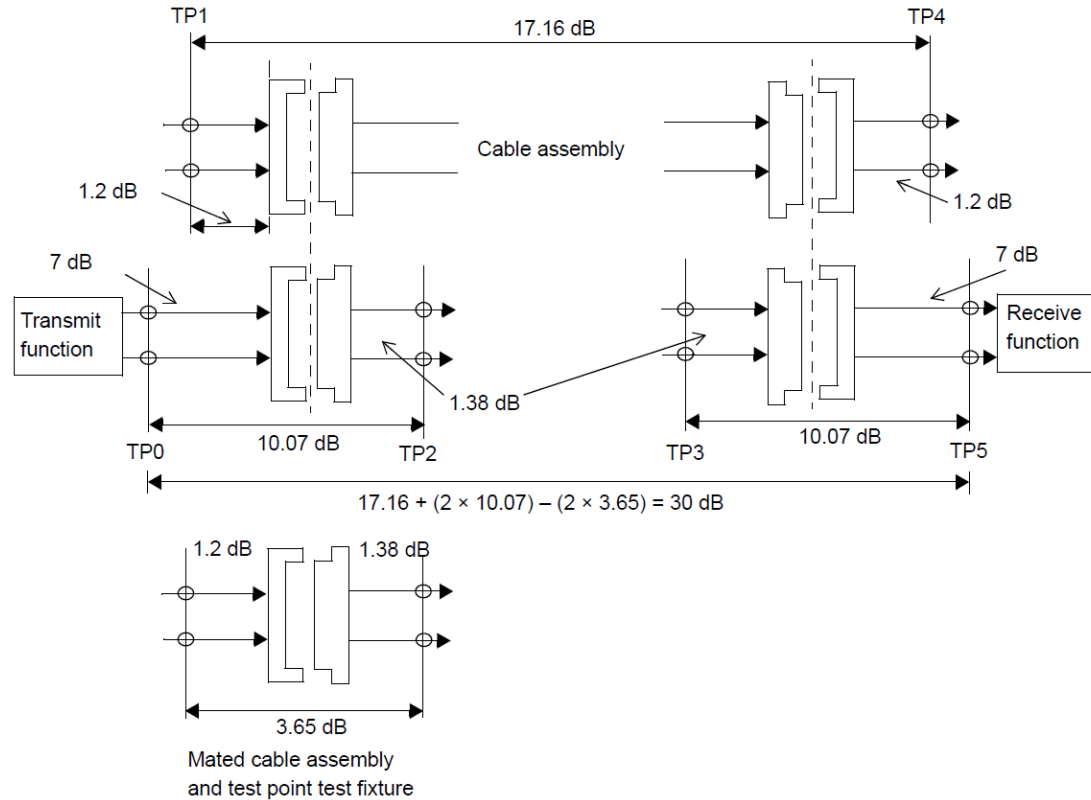


Figure 120E-3—400GAUI-8 chip-to-module insertion loss budget at 13.28 GHz

Total channel link budget (ball to ball) = 10.2dB at 13.28GHz

Source: IEEE802.3bs

200GBASE-CR4 Channel IL Budget



NOTE—The connector insertion loss is 1.07 dB for the mated test fixture. The host connector is allocated 0.62 dB of additional margin.

Figure 136A-1—30 dB channel insertion loss budget at 13.28 GHz

Source: IEEE802.3cd